



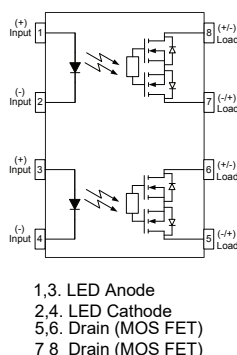
Parameter	Symbol	Rating	Units
Load Voltage	V_L	400	V
Load Current	I_L	0.35	A
On Resistance	R_{on}	3.65	Ω
Output Capacitance	C_{out}	330	pF
I/O Breakdown Voltage	V_{iso}	5000	Vrms



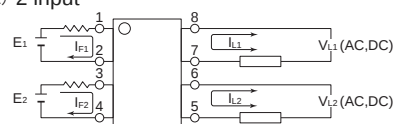
SMD-8



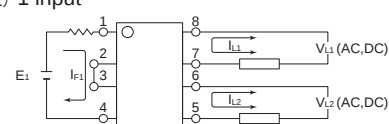
DIP-8



(1) 2 input



(2) 1 input



PhotoRelays

Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

- Long life (No limit on mechanical and electrical lifetime) Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI
- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

Function

PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source configuration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

Applications

These advantages make Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems
- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

TPYES

Category	Output Rating		Package	Part No.	Packing Quantity
	Load Voltage	Load Current			
AC/DC	400V	350mA	DIP-8	GAQW274G1E	50pcs /tube
			SMD-8	GAQW274G1EH	1000pcs /reel

Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Value	Units	Note
Input	Continuous LED Current	I _F	50	mA	
	Peak LED Current	I _{FP}	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	V _R	5	V	
	Input Power Dissipation	P _{In}	75	mW	
Output	Load Voltage	V _L	400	V(DC peak or AC)	
	Load Current	I _L	0.35	A	
	Peak Load Current	I _{Peak}	0.80	A	100ms(1 pulse)
	Output Power Dissipation	P _{out}	450	mW	
Total Power Dissipation		P _T	500	mW	
I/O Breakdown Voltage		V _{I/O}	5000	V _{rms}	RH=60%, 1min
Operating Temperature		T _{opr}	-40 to 85	°C	
Storage Temperature		T _{stg}	-40 to 100	°C	
Pin Soldering Temperature		T _{sol}	260	°C	10 sec max.

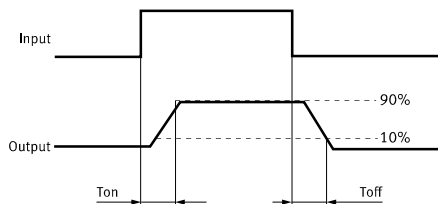
Electrical Characteristics (Ta = 25°C)

Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions
Input *	LED Forward Voltage	V _F	1.24	1.30	1.50	V	I _F =10mA
	LED trigger current	I _{FT}		0.7	3.0	mA	
	Input Current (ON)	I _{F(ON)}		5.0	30.0	mA	
	Input Voltage (OFF)	V _{F(OFF)}	0.7			V	

* The threshold for device switching is I_F ≥ 3.0 mA(MAX.); however, to ensure satisfactory performance of the device across the temperature range, taking into account both circuit loss and interference, it is recommended to operate when the working condition is:
I_F (input current) ≥ 5 mA and ≤ 30mA

Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions
Output	On-Resistance	R _{on}		3.65	5.5	Ω	I _F =5mA, I _L =100mA, Time to flow is within 1 sec.
	Off-State Leakage Current	I _{Leak}		0.01	0.1	uA	V _L =Rating
	Output Capacitance	C _{out}		330		pF	V _L =0, f=1MHz
Transmis sion*	Turn-On Time	T _{on}		0.10	0.3	ms	I _F =5mA, I _L =100mA,
	Turn-Off Time	T _{off}		0.04	0.1	ms	
Coupled	I/O Isolation Resistance	R _{I/O}	10 ¹⁰			Ω	DC500V
	I/O Capacitance	C _{I/O}		0.8	1.5	pF	f=1MHz

*Turn on/Turn off time



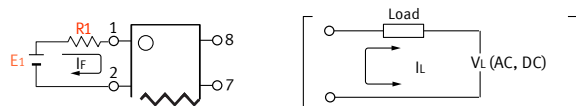
Recommended Operating Conditions

Ensure satisfactory performance of the device across the temperature range, taking into account both circuit loss and interference, it is recommended to operate when the working condition is:

Characteristic	Symbol	Min	Typ.	Max	Unit
Forward current	I_F	5.0	10	30	mA

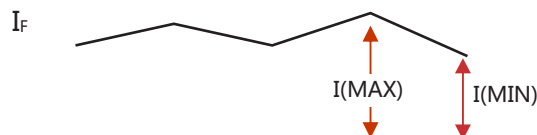
Using Methods

Examples of resistance value to control LED forward current ($I_F=5\text{mA}$)



E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω

LED forward current must be more than 3mA , at $I(\text{MIN})$, and less than 30mA , at $I(\text{MAX})$.



For usage with high reliability, Recommended Operation Conditions is a measure that takes into account the derating of Absolute Maximum Ratings and Electrical Characteristics.

Each item on this list is an independent condition, so it is not simultaneously satisfy several conditions.

Characteristic	Symbol	Min	Typ.	Max	Unit
Load voltage (Peak AC)	V_L	—	—	400	V

Surge voltages at the input

If reverse surge voltages are present at the input terminals, connect a diode in reverse parallel across the input terminals and keep the reverse voltages below the reverse breakdown voltage. Typical circuits are below shown.

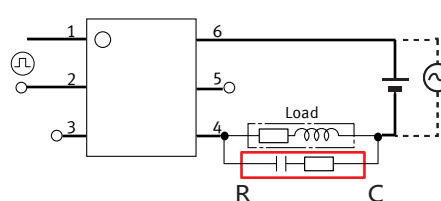
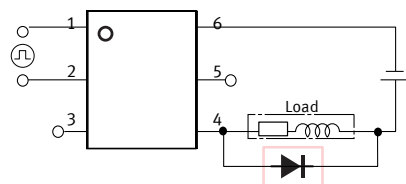


Protection Circuit

Output spike voltages: if an inductive load generates spike voltages which exceed the absolute maximum rating, the spike voltage shall be limited.

Clamp diode is connected in parallel with the load.
Absorb capacity with external diode.

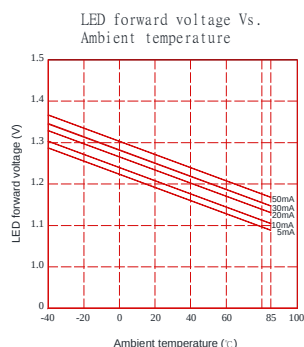
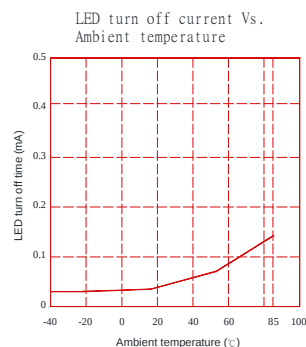
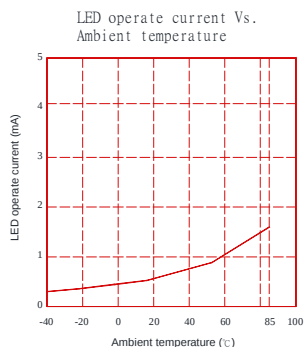
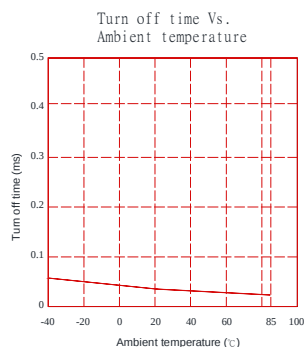
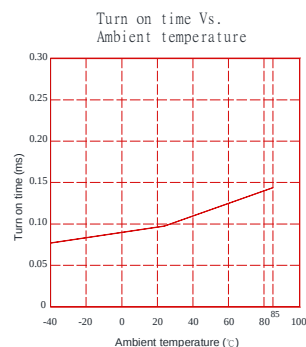
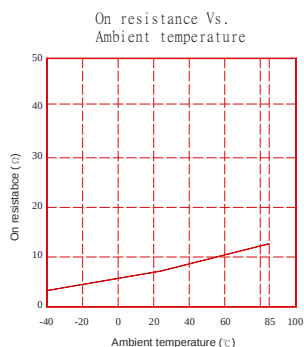
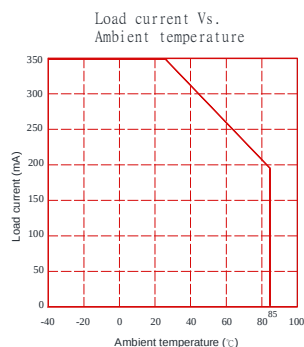
CR Snubber is connected in parallel with the load.
Absorb capacity with buffer capacity.



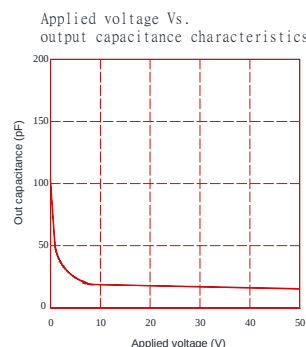
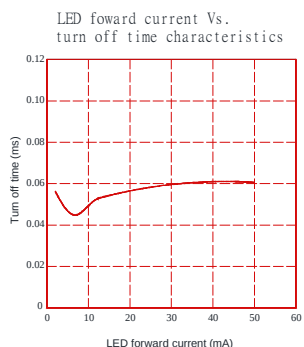
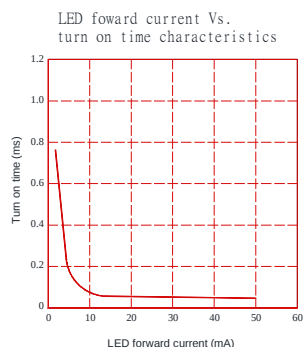
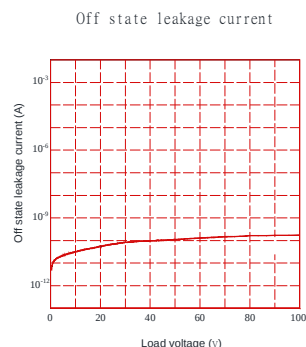
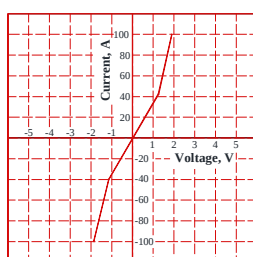
When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective.
Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.

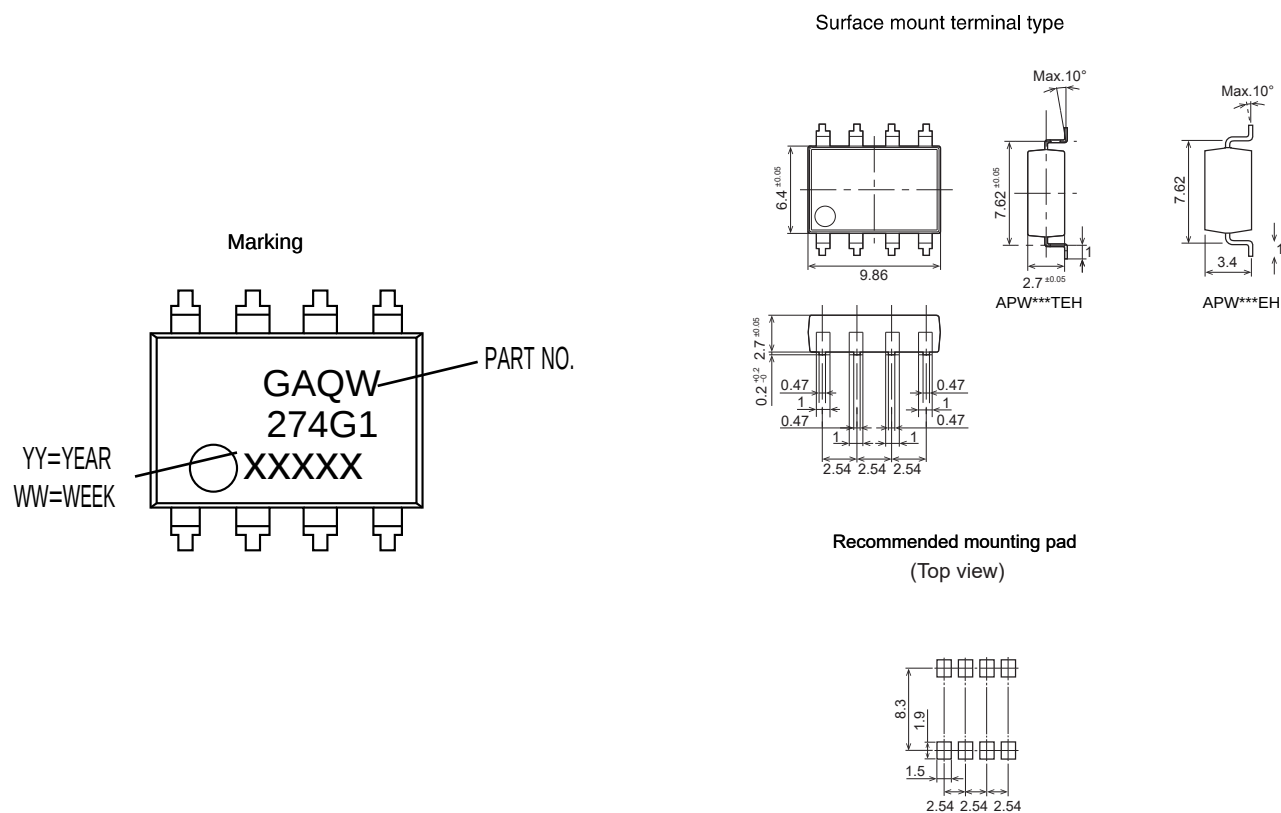
Engineering Data



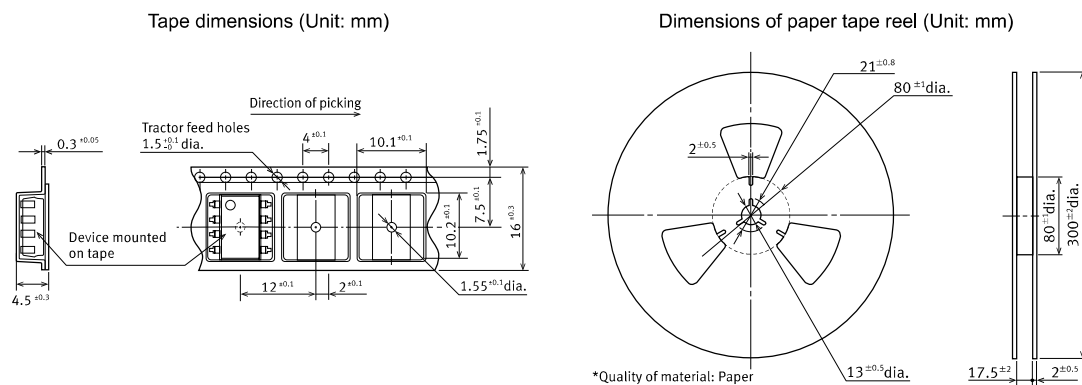
Voltage Vs. current characteristics of output at MOS portion



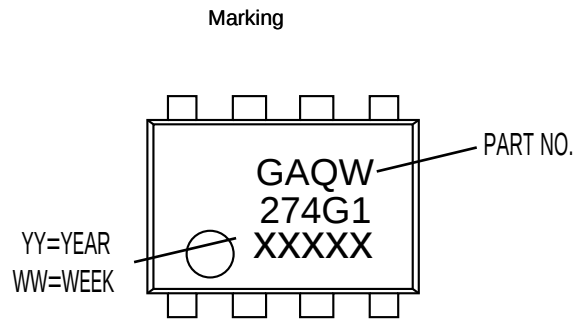
Dimensions and SMD-8 Package Unit: mm



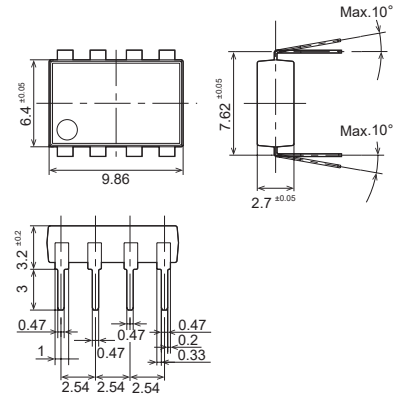
Tape dimensions (tape reel)



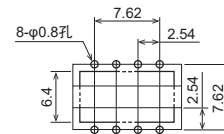
Dimensions and DIP-8 Package Unit: mm



Through hole terminal type

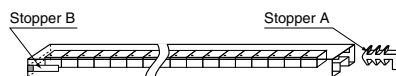


PC board pattern (Bottom view)



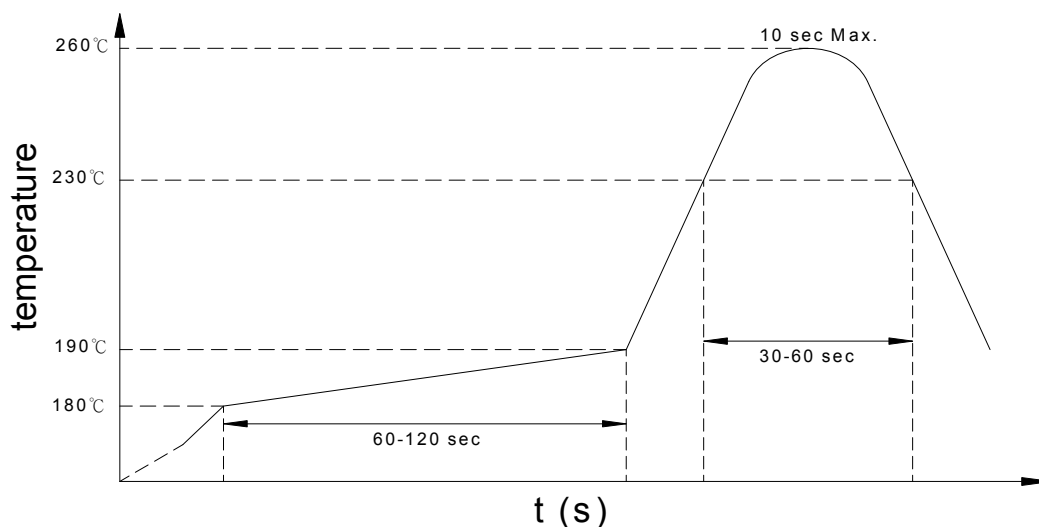
DIP Tape dimensions Unit: mm

Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.



Recommended Soldering Conditions**(a) Infrared reflow soldering :**

- Peak reflow soldering : 260°C or below (package surface temperature)
- Time of peak reflow temperature : 10 sec
- Time of temperature higher than 230°C : 30-60 sec
- Time to preheat temperature from 180~190°C : 60-120 sec
- Time(s) of reflow : Two
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow**(b) Wave soldering :**

- Temperature : 260°C or below (molten solder temperature)
- Time : 10 seconds or less
- Preheating conditions : 120°C or below (package surface temperature)
- Time(s) of reflow : One
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(c) Cautions :

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. SUPSiC classifies its plastic encapsulated devices for moisture sensitivity according to the latest revision of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL)** classification as shown below, and should be handled according to the requirements of the latest revision of the joint industry standard **IPC/JEDEC J-STD-033**.

Moisture Sensitivity Level (MSL) Classification
MSL 3

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard **JESD-625**.

Board Wash

SUPSiC recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.

Post high-temperature welding, direct cleaning with dry ice is prohibited.

